

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Sakae Koyata</td><td>12/20/2006</td></tr><tr><td>Tomohiro Hashii</td><td>12/20/2006</td></tr><tr><td>Katsuhiko Murayama</td><td>12/20/2006</td></tr><tr><td>Kazushige Takaishi</td><td>12/20/2006</td></tr><tr><td>Takeo Katoh</td><td>12/20/2006</td></tr></tbody></table>	Name	Execution Date	Sakae Koyata	12/20/2006	Tomohiro Hashii	12/20/2006	Katsuhiko Murayama	12/20/2006	Kazushige Takaishi	12/20/2006	Takeo Katoh	12/20/2006	
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Tomohiro Hashii	12/20/2006												
Katsuhiko Murayama	12/20/2006												
Kazushige Takaishi	12/20/2006												
Takeo Katoh	12/20/2006												
RECEIVING PARTY DATA													
Name:	SUMCO CORPORATION												
Street Address:	2-1, Shibaura 1-chome												
City:	Minato-Ku, Tokyo												
State/Country:	JAPAN												
PROPERTY NUMBERS Total: 1													
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11669431</td></tr></tbody></table>	Property Type	Number	Application Number:	11669431									
Property Type	Number												
Application Number:	11669431												
CORRESPONDENCE DATA													
Fax Number:	(212)521-5450												
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ATTORNEY DOCKET NUMBER:	JG-SU-5268/500577.20103												
NAME OF SUBMITTER:	Jules E. Goldberg												
Total Attachments: 5 source=Assignment#page1.tif													

CH 11669431 \$40.00

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PATENT
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**ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA**

Whereas, I/ We Sakae Koyata
residing at: c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan

(hereafter "Assignor") has invented certain new and useful improvements in
Title: SINGLE WAFER ETCHING APPARATUS AND SINGLE WAFER ETCHING METHOD
which application for Letters Patent in the United States of America has been filed.

And Whereas, SUMCO CORPORATION of 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan

(hereinafter "Assignee") is desirous of acquiring an interest therein and in the Letters Patent to be obtained therefor:

Now, therefore, be it known by all whom it may concern, that for good and valuable consideration (the sufficiency of which is hereby acknowledged) the Assignor has assigned, transferred and set over, and by these presents does assign, transfer and set over unto the said Assignee for all the countries in the world, the full and exclusive right, title, and interest in and to the said invention, as fully set forth and described in the specification, and any patent issuing thereon

A. prepared and executed on

B. filed in the U.S. Patent and Trademark Office under Application No. 11/669,431
on 1/31/07 including any division, continuation, substitute or renewal application thereof; said invention, application and Letters Patent to be held and enjoyed by the said Assignee to the full end of the term for which said Letters Patent is granted, as fully and entirely as the same would have been held by the Assignor had this assignment and transfer not been made.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 20th day of
December 2006

INVENTOR(S):

Sakae Koyata

Name

Sakae, Koyata.

Signature

20. Dec. 2006

Date

WITNESS: _____

Signature

Date

ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA

Whereas, I/ We Tomohiro Hashii
residing at: c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan
(hereafter "Assignor") has invented certain new and useful improvements in
Title: SINGLE WAFER ETCHING APPARATUS AND SINGLE WAFER ETCHING METHOD
which application for Letters Patent in the United States of America has been filed.

And Whereas, SUMCO CORPORATION of 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan
(hereinafter "Assignee") is desirous of acquiring an interest therein and in the Letters Patent to be obtained
therefor:

Now, therefore, be it known by all whom it may concern, that for good and valuable consideration (the
sufficiency of which is hereby acknowledged) the Assignor has assigned, transferred and set over, and by these
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assignment and transfer not been made.

Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and
all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 20th day of
December 2006

INVENTOR(S):

<u>Tomohiro Hashii</u>	<u>Tomohiro Hashii</u>	<u>20 Dec. 2006</u>
Name	Signature	Date

WITNESS: _____ / _____
Signature Date

**ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA**

Whereas, I/ We Katsuhiko Murayama
residing at: c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan

(hereafter "Assignor") has invented certain new and useful improvements in
Title: SINGLE WAFER ETCHING APPARATUS AND SINGLE WAFER ETCHING METHOD
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Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 20th day of
December 2006

INVENTOR(S):

Katsuhiko Murayama

Name

Katsuhiko Murayama
Signature

20. Dec. 2006
Date

WITNESS: _____

Signature

Date

ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA

Whereas, I/ We Kazushige Takaishi
residing at: c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan
(hereafter "Assignor") has invented certain new and useful improvements in
Title: SINGLE WAFER ETCHING APPARATUS AND SINGLE WAFER ETCHING METHOD
which application for Letters Patent in the United States of America has been filed.

And Whereas, SUMCO CORPORATION of 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan
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Assignor hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and
all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 20th day of
December 2006

INVENTOR(S):

Kazushige Takaishi Kazushige Takaishi 120/Dec/2006
Name Signature Date

WITNESS: _____
Signature Date

ASSIGNMENT - PATENT APPLICATION
UNITED STATES OF AMERICA

Whereas, I/ We Takeo Katoh
residing at: c/o SUMCO CORPORATION, 2-1, Shibaura 1-chome, Minato-ku, Tokyo Japan
(hereafter "Assignor") has invented certain new and useful improvements in
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all such Letters Patent for said invention to said Assignee.

In testimony whereof, the Assignor has hereunto set his hand this 20th day of
December 2006

INVENTOR(S):

<u>Takeo Katoh</u>	<u>Takeo Katoh</u>	<u>20/12/2006</u>
Name	Signature	Date

WITNESS: _____	_____
Signature	Date